Haocheng Dai

Contact Information

aarentai@outlook.com, +1(801)833-3616
https://users.cs.utah.edu/~haocheng/

Summary

My research interest is centered on developing specialized and trustworthy machine learning tools. My focus extends to, but is not limited to:

- Large Vision Language Models and Retrieval-Augmented Generation [2, 8]
- Trustworthy Machine Learning [2, 3]
- Multimodal Learning and Diffusion Models [1, 2, 5, 8]
- Geometric Deep Learning and Shape Modeling [4, 7, 9, 10]
- Physics-informed Machine Learning [6, 7]

Work Experience

Amazon

Seattle, USA

Applied Scientist-LLM, Shopping Convo Foundation

2024 - Present

Working on the next generation LLM-based conversational shopping assistant Rufus.

Amazon Seattle, USA

Applied Scientist Intern

Design diffusion models for text inpainting [5].

2023 2022

Design vision language models for visual documents understanding [8].

Education

University of Utah

Salt Lake City, USA

Ph.D. in Computer Science

2019 - 2024

Committee: S.C. Joshi (Advisor), M. Bauer, S.Y. Elhabian, P.T. Fletcher, R.M. Kirby

Tongji University

Shanghai, China

B.Eng. in Computer Science and Technology

2015 - 2019

Institut de Mathématiques de Toulouse

Exchange Student in Mathematics

Toulouse, France 2019

Technion - Israel Institute of Technology

Haifa, Israel

Exchange Student in Electrical Engineering

2018

Publications & Preprints

- 1. Therapy-Agnostic Prognostication of Prostate Cancer via MR Imaging and Clinical Data Integration. <u>H. Dai</u>, G. Nelson, G. Morrell, J. Tward, S. Joshi, *In Submission to IEEE International Symposium on Biomedical Imaging (ISBI) 2025*, §.
- 2. Refining Skewed Perceptions in Vision-Language Models through Visual Representations. H. Dai, S. Joshi, *In Submission to Conference on Computer Vision and Pattern Recognition* (CVPR) 2025, **©**.
- 3. The Silent Majority: Demystifying Memorization Effect in the Presence of Spurious Correlations, C. You*, <u>H. Dai</u>*, Y. Min*, J. Sekho, S. Joshi, J. Duncan (*equal contribution), *In Submission to Nature Communications*, **9**.
- 4. High-Fidelity CT on Rails-Based Characterization of Delivered Dose Variation in Conformal Head and Neck Treatments, <u>H. Dai</u>, V. Sarkar, C. Dial, M. Foote, Y. Hitchcock, S.

- 5. Detect Al-generated Images Uploaded for Risk Evidence Collection in Customer Self-Service Workflow, <u>H. Dai</u>, S. Chen, B. Xiao, Y. Chen, *Amazon Machine Learning Conference (AMLC) 2023*, §.
- 6. Neural Operator Learning for Ultrasound Tomography Inversion, <u>H. Dai</u>*, M. Penwarden*, R. M. Kirby, S. Joshi (*equal contribution), *International Conference on Medical Imaging with Deep Learning (MIDL) 2023*, §.
- 7. Modeling the Shape of the Brain Connectome via Deep Neural Networks, <u>H. Dai</u>, M. Bauer, P. T. Fletcher, S. Joshi, *International Conference on Information Processing in Medical Imaging (IPMI) 2023*, Oral Presentation, §.
- 8. Understanding Visual Documents from Customer Self-Service Workflow using Multimodal Transformer, <u>H. Dai</u>, J. Chou, S. Chen, B. Xiao, Y. Chen, *Amazon Machine Learning Conference (AMLC) 2022*, **3**.
- 9. Integrated Construction of Multimodal Atlases with Structural Connectomes in the Space of Riemannian Metrics, K. M. Campbell, <u>H. Dai</u>, Z. Su, M. Bauer, P. T. Fletcher, S. Joshi, *Journal of Machine Learning for Biomedical Imaging (MELBA) 2022*, §.
- 10. Structural Connectome Atlas Construction in the Space of Riemannian Metrics, K. M. Campbell, <u>H. Dai</u>, Z. Su, M. Bauer, P. T. Fletcher, S. Joshi, *International Conference on Information Processing in Medical Imaging (IPMI) 2021*, François Erbsmann Prize (**Best Paper Award**), §.

Services Reviewer

- Conferences: ACM MM, AISTATS, CVPR, ICLR, ICML, MICCAI, MIDL, NeurIPS
- Journals: ACM TIST, IEEE TNNIS, Medical Image Analysis, MELBA, Scientific Reports
- Workshops: AI for Differential Equations in Science@ICLR, WiCV@ECCV

Honors & Awards

François Erbsmann Prize (Best Paper Award), *IPMI 2021*Department Fellowship, *School of Computing, University of Utah*Scholarship for France Excellence Summer School, *French Embassy in China*Scholarship for Summer School of Technion, *CHE of Israel & Technion*Chinese Government Scholarship, *Chinese Scholarship Council*Tongji Scholarship of Excellence (2016, 2017, 2018), *Tongji University*

Technical Skills

Python, MatLab, C++, PyTorch